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(54) **SYSTEM AND METHOD FOR THERMAL MANAGEMENT OF REMOVABLE COMPONENTS**
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(57) **ABSTRACT**

Methods, systems, and devices for providing computer implemented services are disclosed. To provide the computer implemented services, the quantity of hardware resources available for providing the computer implemented services may be modified. The quantity of hardware resources may be modified by adding removable cards to a host system. The host system may, while the added removable cards are cold, selectively warm the removable cards through conduction heating to retain their temperatures within operating temperature ranges.

